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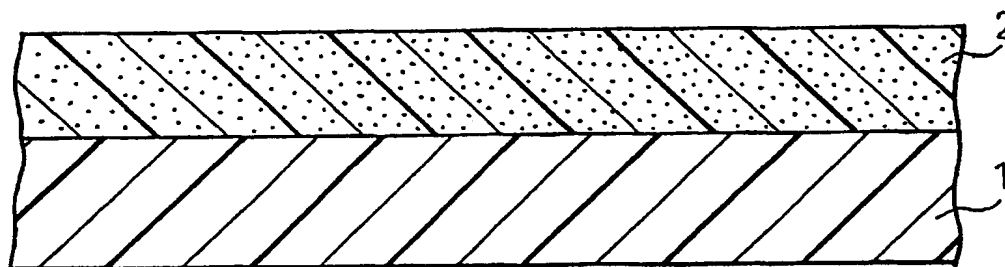
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(54) Title: **PRESSURE SENSITIVE ADHESIVE SHEET AND PRODUCTION METHOD THEREOF**



(57) Abstract: Problem to be solved: to provide a simple method for improving the adhesive property between a fluorine-containing material substrate and a pressure sensitive adhesive which are poor in the adhesion to each other. Means to solve the problem: when a fluorine-containing material substrate having coated thereon a pressure sensitive adhesive is irradiated with an electron beam, a chemical bond is formed between the substrate and the pressure sensitive adhesive. Furthermore, the pressure sensitive adhesive can be cured by polymerization and also the substrate can be cross-linked.

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